



RESPONSE UNDER 37 C.F.R. §1.116  
EXPEDITED PROCEDURE  
EXAMINING GROUP 2814

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Kazutaka SHIBATA

Application No.: 09/588,628

Filed: June 7, 2000

For: SEMICONDUCTOR CHIP WITH EXTERNAL CONNECTING TERMINAL (AS AMENDED)

Attorney Docket No.: ROH-023

Examiner: N. Ha

Art Unit: 2814

12/B (N)  
FJONES  
6-6-02

**AMENDMENT AFTER FINAL REJECTION UNDER 37 C.F.R. §1.116**

BOX AF

Commissioner for Patents  
Washington, DC 20231

Sir:

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In response to the final Office Action dated April 5, 2002, please amend the above-identified application as follows:

**IN THE CLAIMS:**

Please amend claims 1 and 7 as set forth below in clean form. Additionally, in accordance with 37 CFR 1.121(c)(1)(ii), amended claim(s) is/are set forth in a marked-up version in the page(s) attached to this Amendment.

1. (Twice Amended) A semiconductor device, comprising:
  - a semiconductor chip;
  - protective resin covering a sidewall of the semiconductor chip and having a surface formed so as to be flush with an inactive surface of the semiconductor chip which is a surface on the opposite side of an active surface of the semiconductor chip;
  - an external connecting terminal electrically connected to the active surface of the semiconductor chip and projecting therefrom; and